

## 20V N-Channel Enhancement Mode MOSFET

### DESCRIPTION

The UCT2300 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density. Advanced trench technology to provide excellent  $R_{DS(ON)}$ .low gate charge and operation gate as 1.8V. This device is suitable for use as a load switch or other general applications.

UCT2300 ROHS Compliant This is Halogen Free

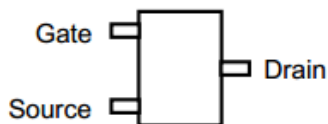
### FEATURE

- 20V/5.8A,  $R_{DS(ON)}=20m\Omega(\text{typ.})@V_{GS}=4.5V$
- 20V/4.0A,  $R_{DS(ON)}=25m\Omega(\text{typ.})@V_{GS}=2.5V$
- 20V/2.8A,  $R_{DS(ON)}=33m\Omega(\text{typ.})@V_{GS}=1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and Maximum DC current capability

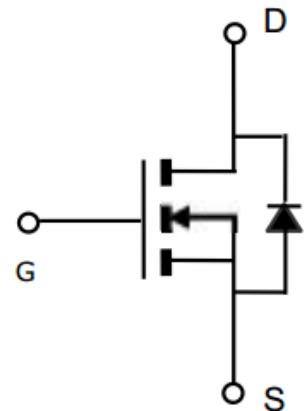
### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- DSC
- LCD Display inverter
- Battery Powered System

### PIN CONFIGURATION



SOT-23L  
Top View



## ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted )

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current ( $T_C=25^\circ\text{C}$ ) <sup>A</sup>	5.8	A
	Continuous Drain Current ( $T_C=70^\circ\text{C}$ ) <sup>A</sup>		
$I_{DM}$	Pulsed Drain Current <sup>B</sup>	14	A
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$	1.2
		$T_A=70^\circ\text{C}$	0.5
$T_J$	Operation Junction Temperature	-55 to 150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## ■ THERMAL DATA

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient <sup>A</sup>	Steady-State	-	120 °C/W
$R_{\theta JL}$	Thermal Resistance Junction to Lead <sup>A</sup>	Steady-State	-	80 °C/W

## ■ ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ Unless otherwise noted )

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5		1	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage, Drain-Source Leakage Current	$V_{DS}=30V, V_{GS}=0V$ $T_J=25^\circ\text{C}$			1	$\mu A$
		$V_{DS}=30V, V_{GS}=0V$ $T_J=55^\circ\text{C}$			5	
$R_{DS(ON)}$	Drain-source On-Resistance <sup>B</sup>	$V_{GS}=4.5V, I_D=3.1A$		20	25	m $\Omega$
		$V_{GS}=2.5V, I_D=2.0A$		25	30	
		$V_{GS}=1.8V, I_D=1.2A$		33	42	
$G_{fs}$	Forward Transconductance	$V_{DS}=25V, I_D=2.5A$		30		S

Source-Drain Doide						
$V_{SD}$	Diode Forward Voltage	$I_S=1.7A, V_{GS}=0V$		0.6	1.2	V
$I_S$	Continuous Source Current <sup>AD</sup>				6	A
Dynamic Parameters						
$Q_{g(4.5V)}$	Total Gate Charge	$V_{DS}=15V$		7.7		nC
$Q_{gs}$	Gate-Source Charge	$V_{GS}=4.5V$		1.1		nC
$Q_{gd}$	Gate-Drain Charge	$I_D=3.1A$		2.35		nC
$C_{iss}$	Input Capacitance	$V_{DS}=15V$		650		pF
$C_{oss}$	Output Capacitance	$V_{GS}=0V$		92		pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1MHz$		75		pF
$t_{d(on)}$	Turn-On Time	$V_{DD}=15V$		19.1		nS
$t_r$	Turn-OffTime	$I_D=1.0A$		135		nS
$t_{d(off)}$	Total Gate Charge	$V_{GEN}=4.5V$		90		nS
$t_f$	Gate-Source Charge	$R_G=6\Omega$		116		nS

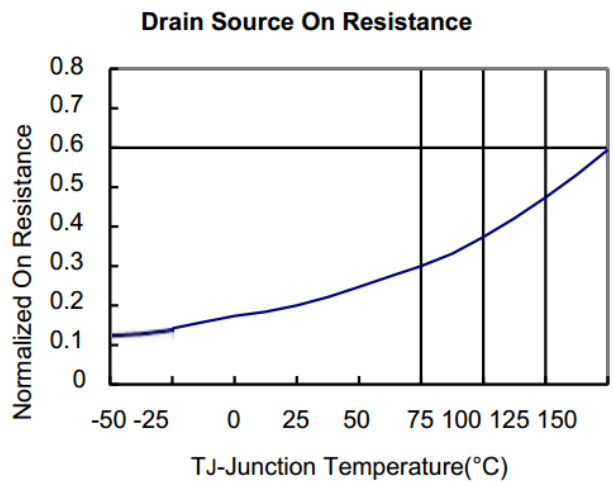
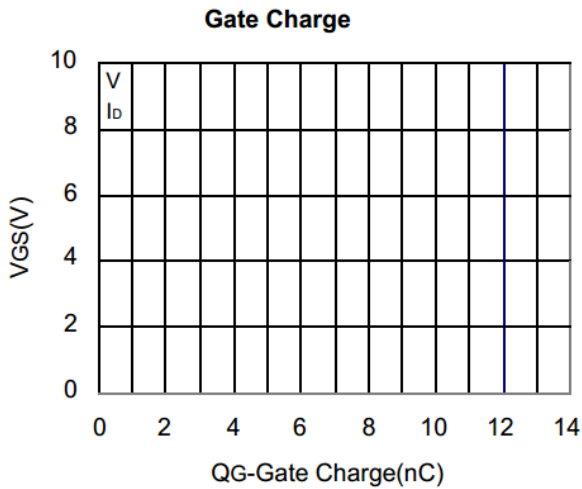
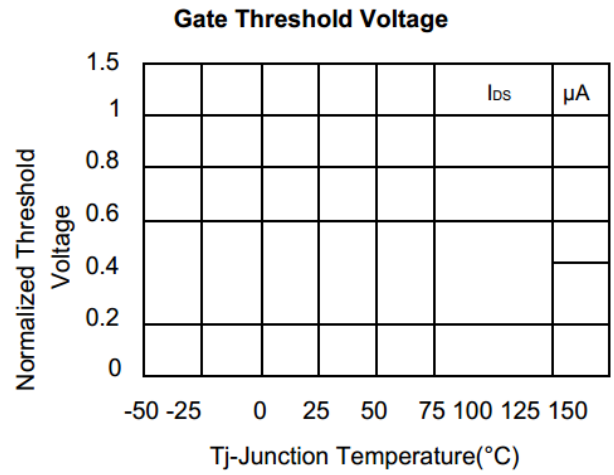
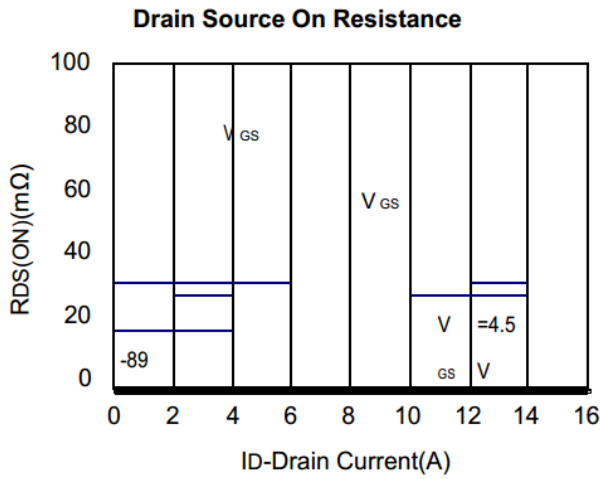
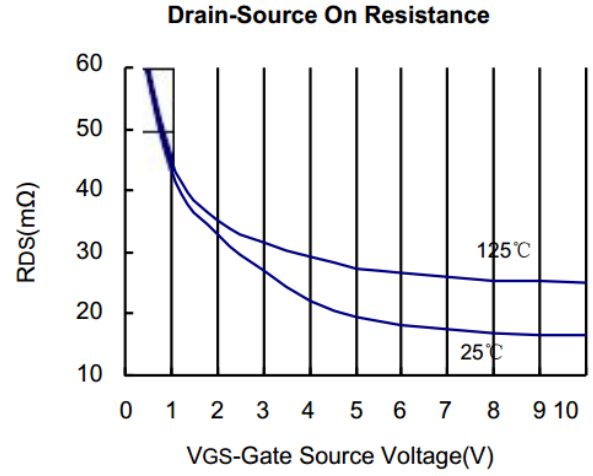
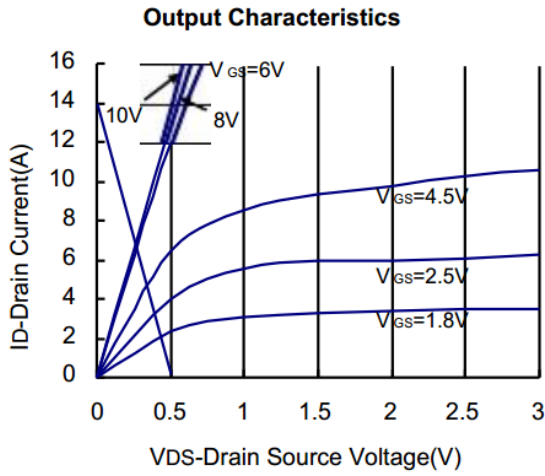
**Note:**

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ .
- The data tested by pulsed , pulse width  $\cong 300\mu S$  , duty cycle  $\cong 2\%$
- The EAS data shows Max. rating . The test condition is  $V_{DD}=20V, V_{GS}=12V, L=0.1mH$ .
- The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

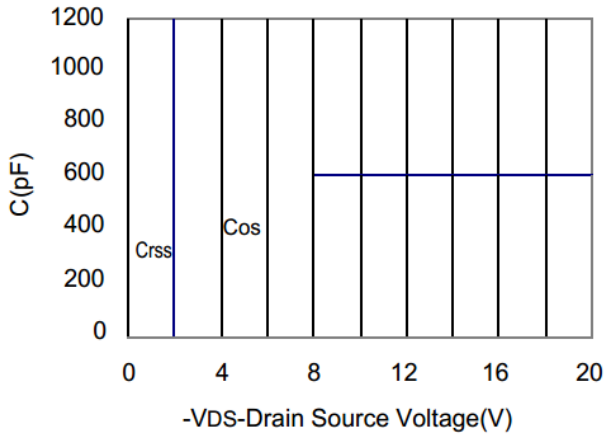
We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.

■ TYPICAL CHARACTERISTICS (25°C Unless Note)

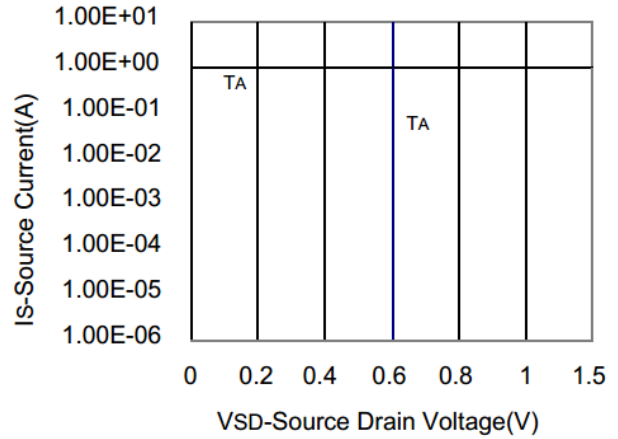


■ TYPICAL CHARACTERISTICS (25°C Unless Note)

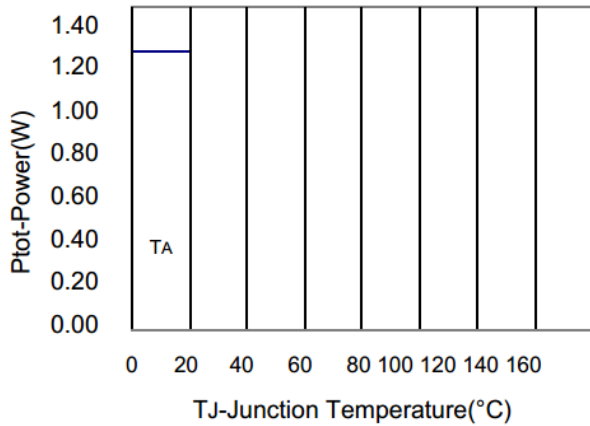
**Capacitance**



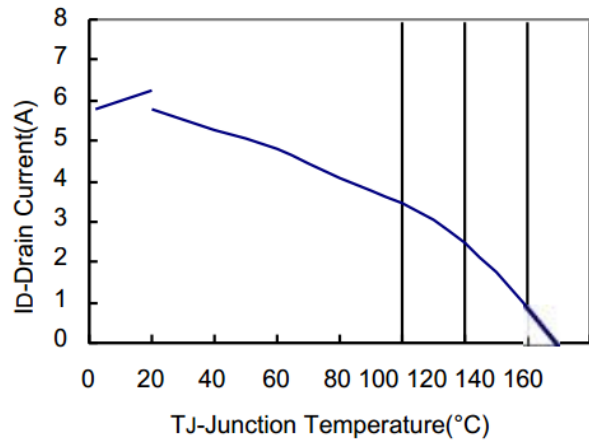
**Source Drain Diode Forward**



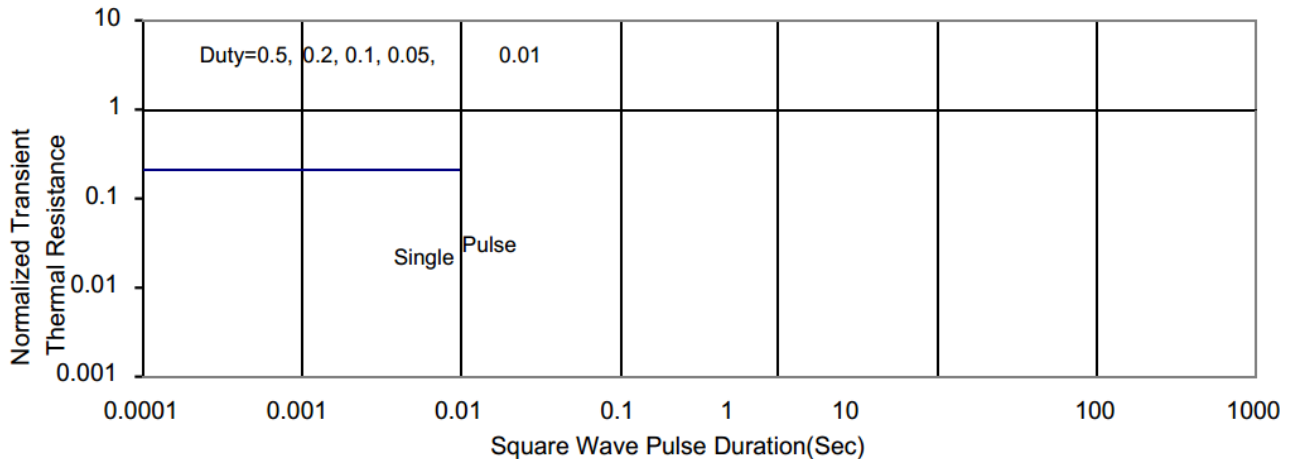
**Power Dissipation**



**Drain Current**



**Thermal Transient Impedance**



## ■ SOT-23L PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°

